


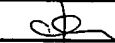

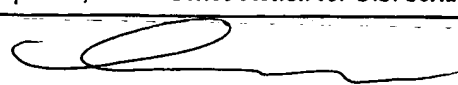


INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)				ATTY. DOCKET NO. 006365 USA/ MTCG/PCTRL		SERIAL NO. 10/712,273	
				APPLICANT Yuri KOKOTOV et al.			
				FILING DATE November 14, 2003		GROUP	
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S	4,957,605	09/18/90	Hurwitt et al.			04/17/89	
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	5,444,837	08/22/95	Bomans et al.			12/29/93	
	5,665,214	09/09/97	Iturralde			05/03/95	
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	EP 0 932 195 A1	07/28/99	EP			X	
	EP 1 083 470 A2	03/14/01	EP			X	
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006365 USA/MTCG/PCTRLSERIAL NO.
10/712,273APPLICANT
Yuri KOKOTOV et al.FILING DATE
November 14, 2003

GROUP

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	5,654,903	08/05/97	Reitman et al.			11/07/95
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	5,825,913	10/20/98	Rostami et al.			07/18/95
	5,838,595	11/17/98	Sullivan et al.			11/25/96
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	WO 99/25520	05/27/99	WO			X	
	WO 00/00874	01/06/00	WO			X	

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

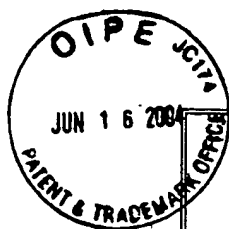
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EXAMINER

DATE CONSIDERED

11/11/04

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INFORMATION DISCLOSURE
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ATTY. DOCKET NO.
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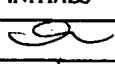


SERIAL NO.
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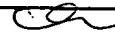


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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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	4,938,600	07/03/90	Into			02/09/89
	4,967,381	10/30/90	Lane et al.			07/06/89
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EXAMINER 	DATE CONSIDERED 11/11/04					

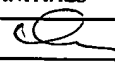
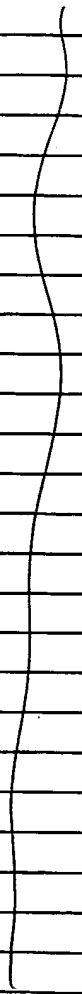
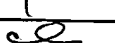

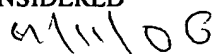
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	5,719,495	02/17/98	Moslehi			06/05/96	
	5,719,796	02/17/98	Chen			12/04/95	
	5,735,055	04/07/98	Hochbein et al.			04/23/96	
	5,740,429	04/14/98	Wang et al.			07/07/95	
EXAMINER			DATE CONSIDERED				
			11/11/03				


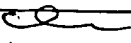

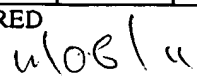
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	5,910,846	06/08/99	Sandhu			08/19/97	
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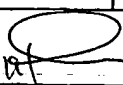
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				APPLICANT Yuri KOKOTOV et al.			
				FILING DATE November 14, 2003		GROUP	
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
a	5,912,678	06/15/99	Saxena et al.			04/14/97	
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
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U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
[Signature]	2002/0070126 A1	06/13/02	Sato et al.			09/19/01	
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[Signature]	2002/0199082 A1	12/26/02	Shanmugasundram et al.			06/18/02	
EXAMINER [Signature]				DATE CONSIDERED 11/11/03			

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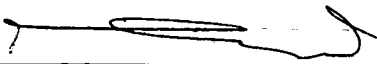
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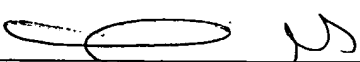
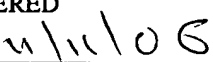
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[illegible]



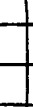

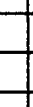
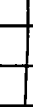



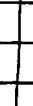




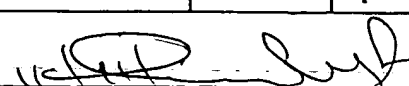
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	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium			
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System			
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder			
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers			
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service			
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems			
	09/800,980	03/08/01	Hawkins et al.	Dynamic and Extensible Task Guide			
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	10/084,092	02/28/02	Araekaparambil et al.	Computer Integrated Manufacturing Techniques			
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				FILING DATE November 14, 2003		GROUP	
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	61-66104	04/04/86	Japan			X	
	61-171147	08/01/86	Japan			X	
	01-283934	11/15/89	Japan			X	
	0 397 924 A1	11/22/90	Europe			X	
	2,050,247	08/29/91	Canada			X	
	2,165,847	08/29/91	Canada			X	
	2,194,855	08/29/91	Canada			X	
	3-202710	09/04/91	Japan			X	
	05-151231	06/18/93	Japan			X	
	05-216896	08/27/93	Japan			X	
	05-266029	10/15/93	Japan			X	
	06-110894	04/22/94	Japan			X	
	06-176994	06/24/94	Japan			X	
	06-184434	07/05/94	Japan			X	
	06-252236	09/09/94	Japan			X	
	06-260380	09/16/94	Japan			X	
	EP 0 621 522 A2	10/26/94	Europe			X	
	WO 95/34866	12/21/95	WO			X	
	8-23166	01/23/96	Japan			X	
	08-50161	02/20/96	Japan			X	
	08-149583	06/07/96	Japan			X	
	08-304023	11/22/96	Japan			X	
	EP 0 747 795 A2	12/11/96	Europe			X	
	09-34535	02/07/97	Japan			X	
	9-246547	09/19/97	Japan			X	
	WO 98/05066	02/05/98	WO			X	
	10-34522	02/10/98	Japan			X	
	10-173029	06/26/98	Japan			X	
EXAMINER 				DATE CONSIDERED 11/11/05			

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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	EP 0 869 652 A2	10/07/98	Europe			X	
	WO 98/45090	10/15/98	WO			X	
	EP 0 877 308 A2	11/11/98	Europe			X	
	EP 0 881 040 A2	12/02/98	Europe			X	
	EP 0 895 145 A1	02/03/99	Europe			X	
	WO 99/09371	02/25/99	WO			X	
	11-67853	03/09/99	Japan			X	
	EP 0 910 123 A1	04/21/99	Europe			X	
	11-126816	05/11/99	Japan			X	
	11-135601	05/21/99	Japan			X	
	WO 99/25520	05/27/99	WO			X	
	EP 0 932 194 A1	07/28/99	Europe			X	
	WO 99/59200	11/18/99	WO			X	
	WO 00/05759	02/03/00	WO			X	
	WO 00/35063	06/15/00	WO			X	
	2000-183001	06/30/00	Japan			X	
	WO 00/54325	09/14/00	WO			X	
	GB 2 347 885 A	09/20/00	United Kingdom			X	
	WO 00/79355 A1	12/28/00	WO			X	
	EP 1 066 925 A2	01/10/01	Europe			X	
	EP 1 067 757 A1	01/10/01	Europe			X	
	EP 1 071 128 A2	01/24/01	Europe			X	
	WO 01/11679 A1	02/15/01	WO			X	
	WO 01/15865 A1	03/08/01	WO			X	
	WO 01/18623 A1	03/15/01	WO			X	
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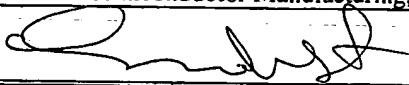
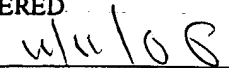
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FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	2001-76982	03/23/01	Japan			X	
	WO 01/25865 A1	04/12/01	WO			X	
	EP 1 092 505 A2	04/18/01	Europe			X	
	WO 01/33277 A1	05/10/01	WO			X	
	WO 01/33501 A1	05/10/01	WO			X	
	434103	05/16/01	Taiwan			X	
	436383B	05/28/01	Taiwan			X	
	WO 01/52055 A3	07/19/01	WO			X	
	WO 01/52319 A1	07/19/01	WO			X	
	WO 01/57823 A2	08/09/01	WO			X	
	455938B	09/21/01	Taiwan			X	
	455976	09/21/01	Taiwan			X	
	2001-284299	10/12/01	Japan			X	
	WO 01/80306 A2	10/25/01	WO			X	
	2001-305108	10/31/01	Japan			X	
	EP 1 072 967 A3	11/21/01	Europe			X	
	2002-9030	01/11/02	Japan			X	
	EP 1 182 526 A2	02/27/02	Europe			X	
	WO 02/17150 A1	02/28/02	WO			X	
	WO 02/31613 A2	04/18/02	WO			X	
	WO 02/31613 A3	04/18/02	WO			X	
	WO 02/33737 A2	04/25/02	WO			X	
	WO 02/074491 A1	09/26/02	WO			X	
	2002-343754	11/29/02	Japan			X	
EXAMINER		DATE CONSIDERED 11/11/06					



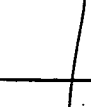



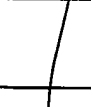







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		APPLICANT Yuri KOKOTOV et al.	
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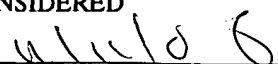
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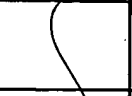

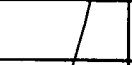
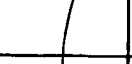
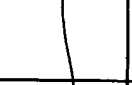
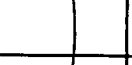
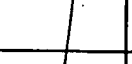
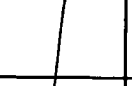
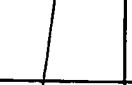
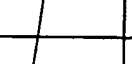
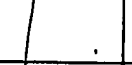

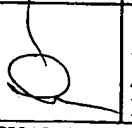


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











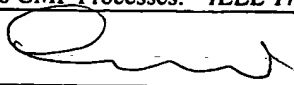

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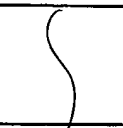



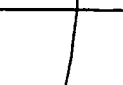
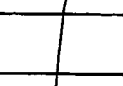
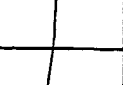
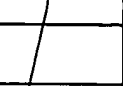

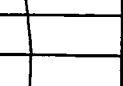
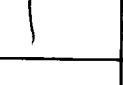


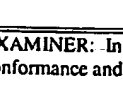
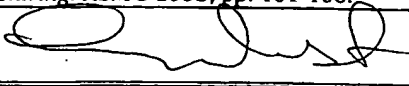

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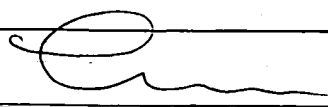

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